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## Low-Power HF Microelectronics A unified approach

This book presents a thorough and integrated treatment of key topics in the field of low-voltage, low-power, mixed-mode design for the manufacture of low-cost, high-performance, robust integrated circuits. It brings together innovative modelling, simulation and design techniques in CMOS, SOI, GaAs and BJT, optimally combining process, device and design knowledge of low-voltage, high-frequency systems, including smart sensors.
The book meets the needs of mixed-signal designers and reflects the rise in high-performance, ultra-low-power digital systems combined with wireless multimedia telecommunications. The text is supported throughout by realistic application examples from both industry and academia, and a wealth of references to literature including many Internet sources.
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It is the merit of this book to assemble an impressive collection of up-to-date and original tutorial contributions from industry and university specialists spanning the whole hierarchy of microelectronics.'
from the Foreword by Professor Eric A. Vittoz

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